



Product Change Notice

Notice: #101008

Date: October 08, 2010

To Our Valued Customers:

We appreciate your use of V•I Chip products. Our commitment to customer satisfaction is demonstrated by our notification to you of the following change.

Description:

The application of Trabond™ adhesive during V•I Chip manufacturing is a legacy process element that was introduced on a prototype, extended J-lead design which was not taken to mass production. The adhesive was subsequently used for the standard J-lead design which is in current production; the Trabond is applied between the J-lead assembly and the molded body of the V•I Chip. Through continuous improvement activities, tests have been performed that show the removal of Trabond improves J-lead to V•I Chip solder interconnect reliability.

Products Affected:

All V.I Chip products (BCM, PRM, and VTM), including both full and half sized chips.

Schedule / Datecodes:

Production change takes effect 12 DEC 2010 (Datecode 1050).

Parts shipped after this date may be from finished goods until stock is depleted

Action Required:

Customers with 2-sided reflow assemblies or, where rework of components is required on the reverse side of the PCB in relation to the V•I Chip, may choose to implement industry-standard chip bond adhesives underneath the V•I Chip.

No change to external fit or form of the V•I Chips.

No change to the thermal or electrical performance.

No change to part numbering.

Parts from old/new process may be used in the same system.

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